

LNPTM THERMOCOMPTM COMPOUND MFOOAS

MFX-100-10

DESCRIPTION

LNP THERMOCOMP MF00AS compound is based on Polypropylene (PP) resin containing 50% glass fiber. Added features of this grade include: Heat Stabilized.

GENERAL INFORMATION	
Features	Heat Stabilized, High stiffness/Strength, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polypropylene, Unspecified (PP, Unspecified)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Consumer	Sport/Leisure, Personal Accessory
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS	
MECHANICAL ⁽¹⁾				
Tensile Stress, break	87	MPa	ASTM D638	
Tensile Strain, break	1.6	%	ASTM D638	
Flexural Stress	149	MPa	ASTM D790	
Flexural Modulus	11030	MPa	ASTM D790	
IMPACT ⁽¹⁾				
Izod Impact, unnotched, 23°C	320	J/m	ASTM D4812	
Izod Impact, notched, 23°C	69	J/m	ASTM D256	
THERMAL ⁽¹⁾				
Relative Temp Index, Elec ⁽²⁾	105	°C	UL 746B	
Relative Temp Index, Mech w/impact ⁽²⁾	105	°C	UL 746B	
Relative Temp Index, Mech w/o impact ⁽²⁾	105	°C	UL 746B	
PHYSICAL ⁽¹⁾				
Density	1.33	g/cm ³	ASTM D792	
Mold Shrinkage, flow, 24 hrs ⁽³⁾	0.2	%	ASTM D955	
Mold Shrinkage, xflow, 24 hrs (3)	0.8	%	ASTM D955	
ELECTRICAL ⁽¹⁾				
Comparative Tracking Index (UL) {PLC}	0	PLC Code	UL 746A	
Hot-Wire Ignition (HWI), PLC 0	≥3	mm	UL 746A	
Hot-Wire Ignition (HWI), PLC 1	≥1.5	mm	UL 746A	
Hot-Wire Ignition (HWI), PLC 3	≥1	mm	UL 746A	
Hot-Wire Ignition (HWI), PLC 4	≥0.75	mm	UL 746A	
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PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
High Amp Arc Ignition (HAI), PLC 0	≥0.75	mm	UL 746A
High Amp Arc Ignition (HAI), PLC 1	≥1.5	mm	UL 746A
High Voltage Arc Track Rate {PLC}	0	PLC Code	UL 746A
Arc Resistance, Tungsten {PLC}	6	PLC Code	ASTM D495
FLAME CHARACTERISTICS (2)			
UL Yellow Card Link	E121562-101283898	-	-
UL Yellow Card Link 2	E121562-101284109	-	-
UL Recognized, 94HB Flame Class Rating	≥0.75	mm	UL 94
INJECTION MOLDING (4)			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Melt Temperature	225 – 250	°C	
Front - Zone 3 Temperature	240 – 250	°C	
Middle - Zone 2 Temperature	215 – 225	°C	
Rear - Zone 1 Temperature	195 – 205	°C	
Mold Temperature	30 – 50	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 - 60	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.

(3) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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